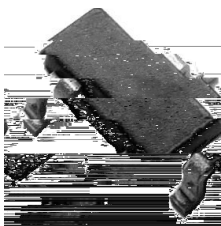
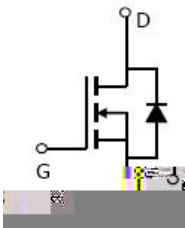


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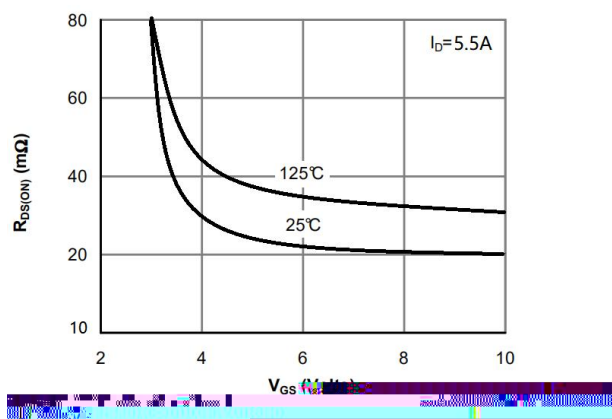
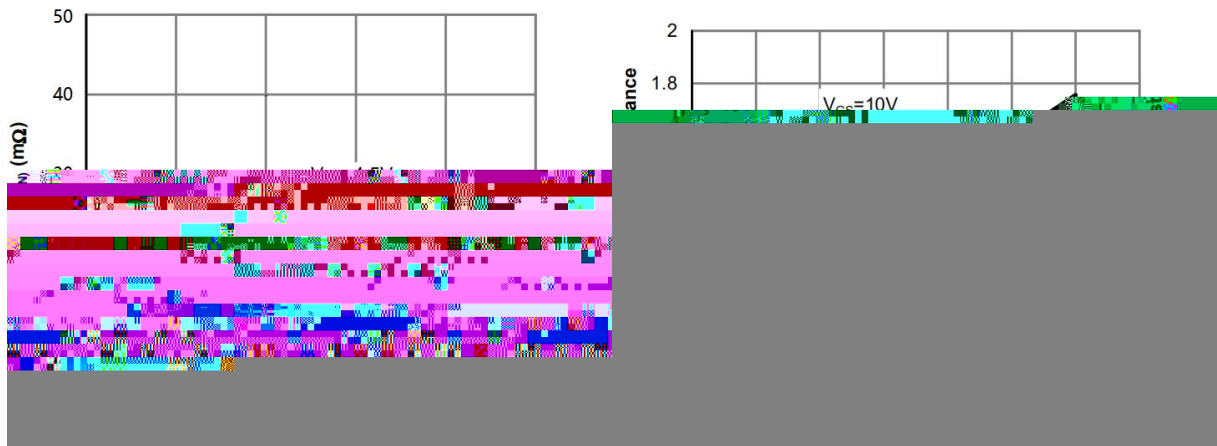
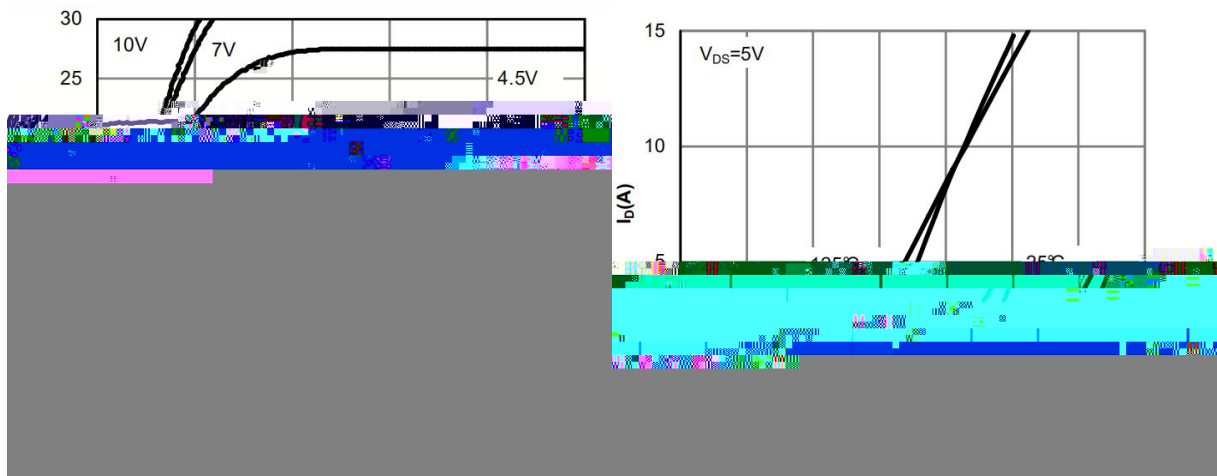


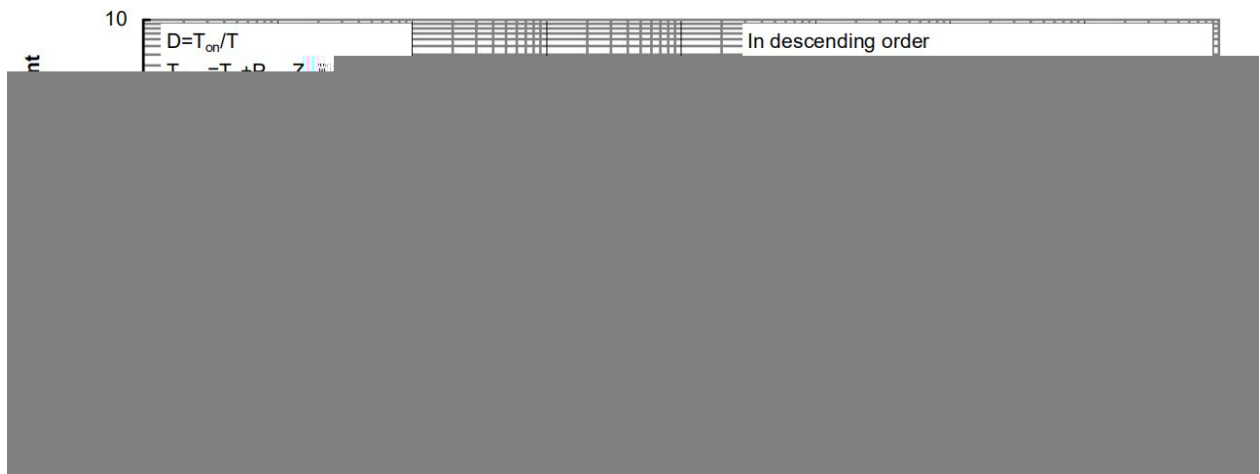
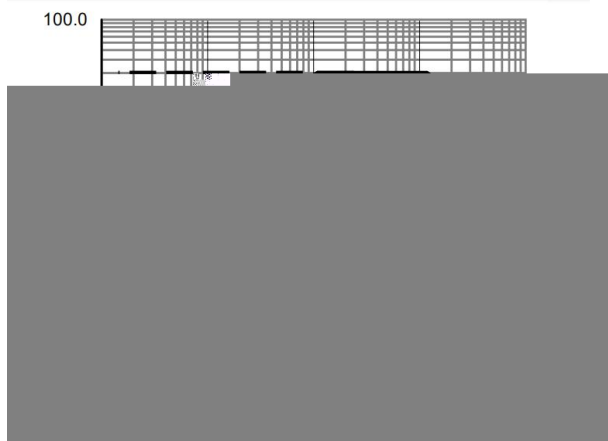
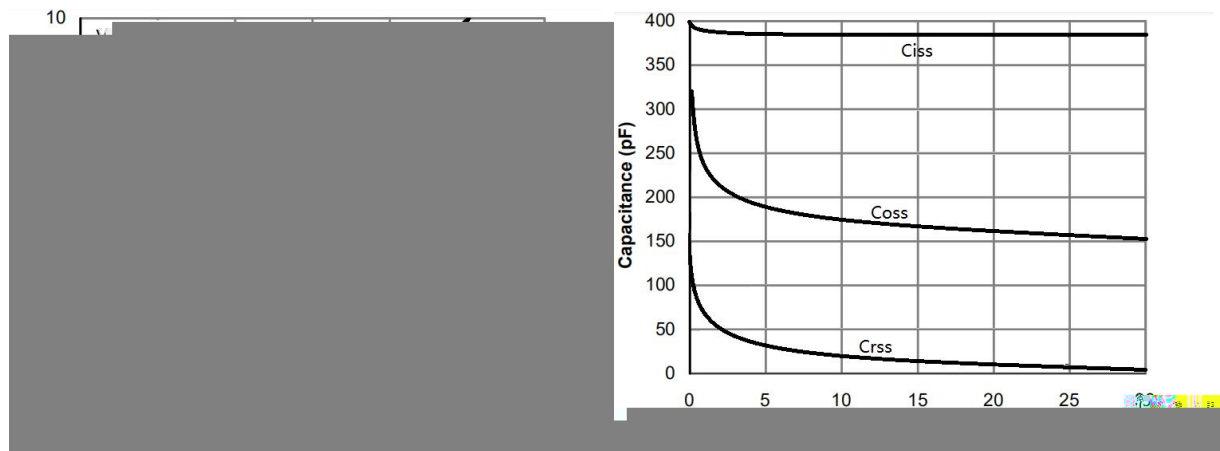
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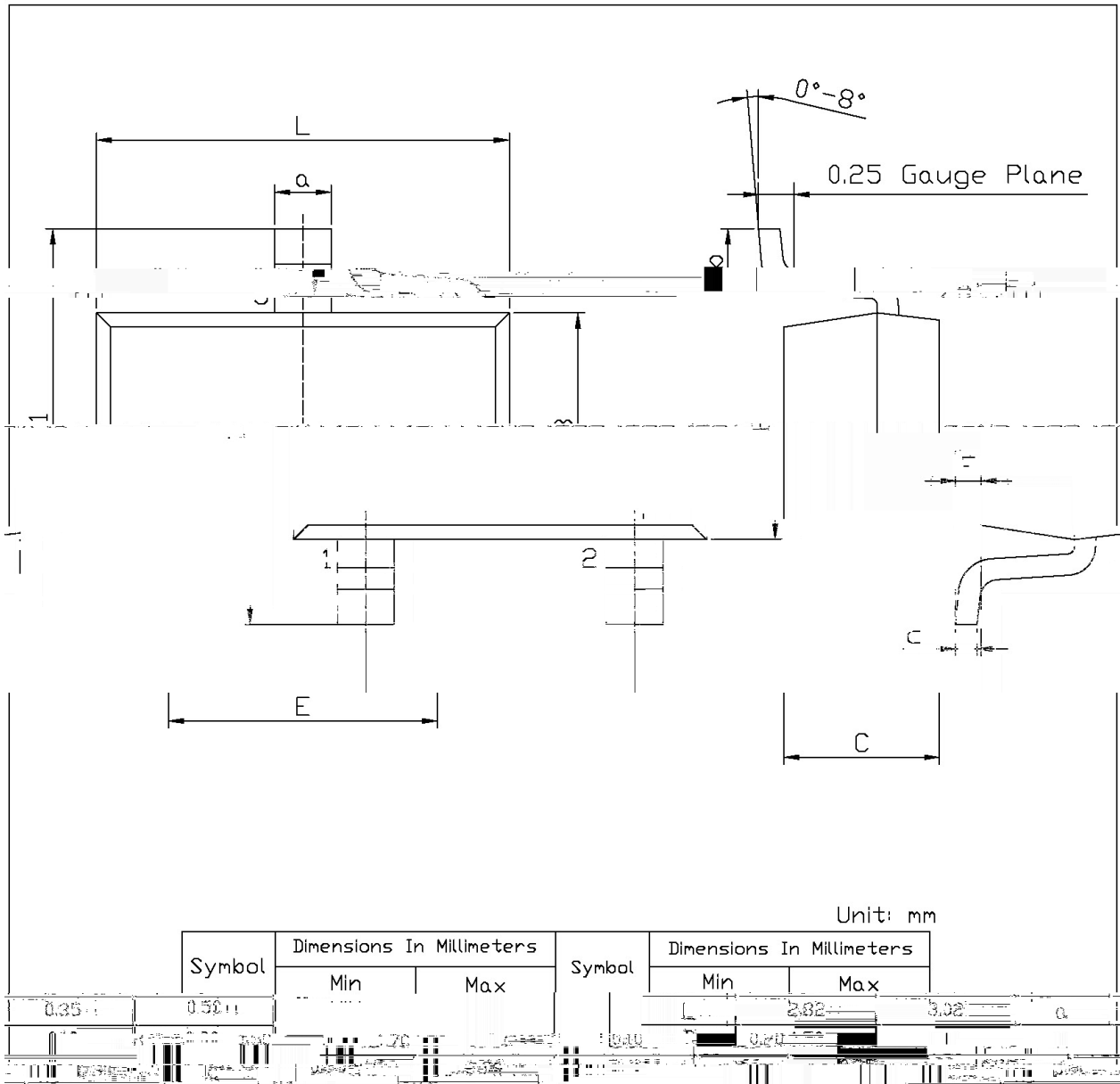


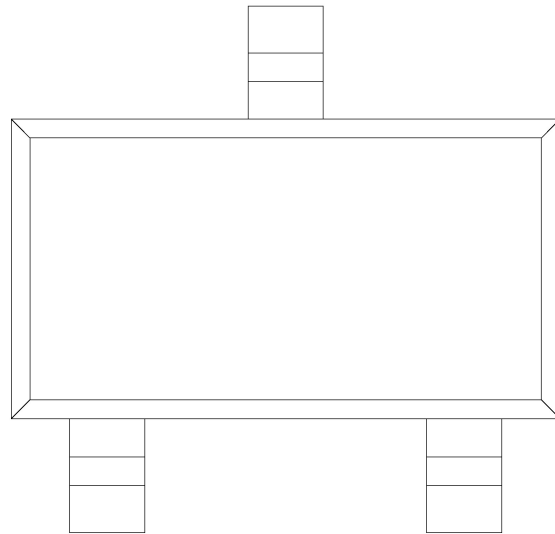
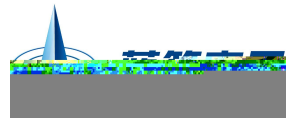
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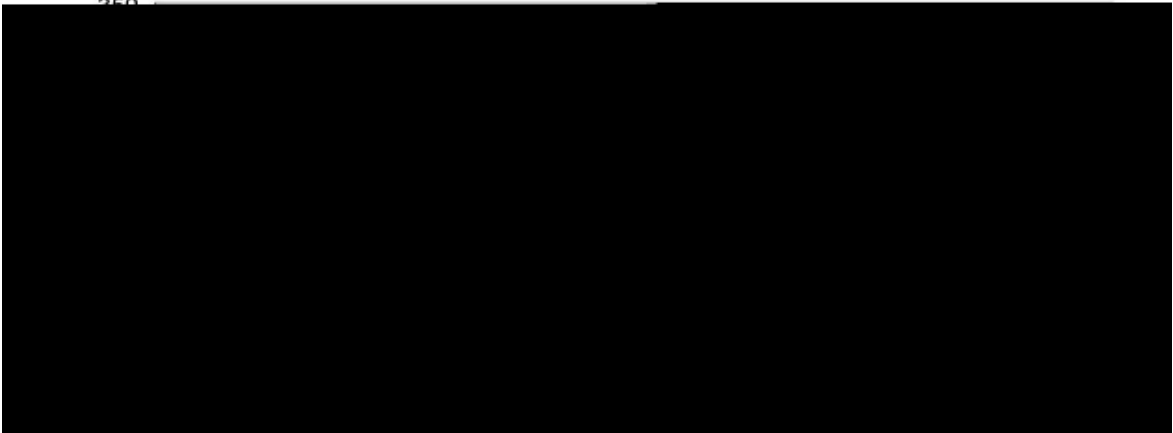




B4
H



Temperature Profile for IR Reflow Soldering(Pb-Free)



± °C ± °C ± °C ± °C

± °C ± °C ± °C ± °C

封装形式	包装数量					包装尺寸		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box 盒	Outer Box 箱
SOT-23-3	3,000	10	30,000	4	120,000	7" ×8	210×205×205	445×230×435